

#### ENABLING ULTIMATE MINIATURIZATION AND CUSTOMIZATION WITH THE LATEST SINGLE CHIP SYSTEM MODULE TECHNOLOGY

#### SCM-i.MX 6SX and 6SX V-link

NAVJOT CHHABRA PRODUCT DEVELOPMENT MANAGER SYSTEM SOLUTIONS ORGANIZATION FTF-MHW-N1990 MAY 18<sup>TH</sup>, 2016

PUBLIC USE



## AGENDA

- Introduction
- Single Chip System Module and 1<sup>st</sup> Product Launch
- Single Chip Module Roadmap
- Introduction to the Two New SCM Products
- Partner Demos
  - Boundry Devices
  - Code
  - FirstView
- Summary
- Q & A





# INTRODUCTION



### New solutions for todays markets.



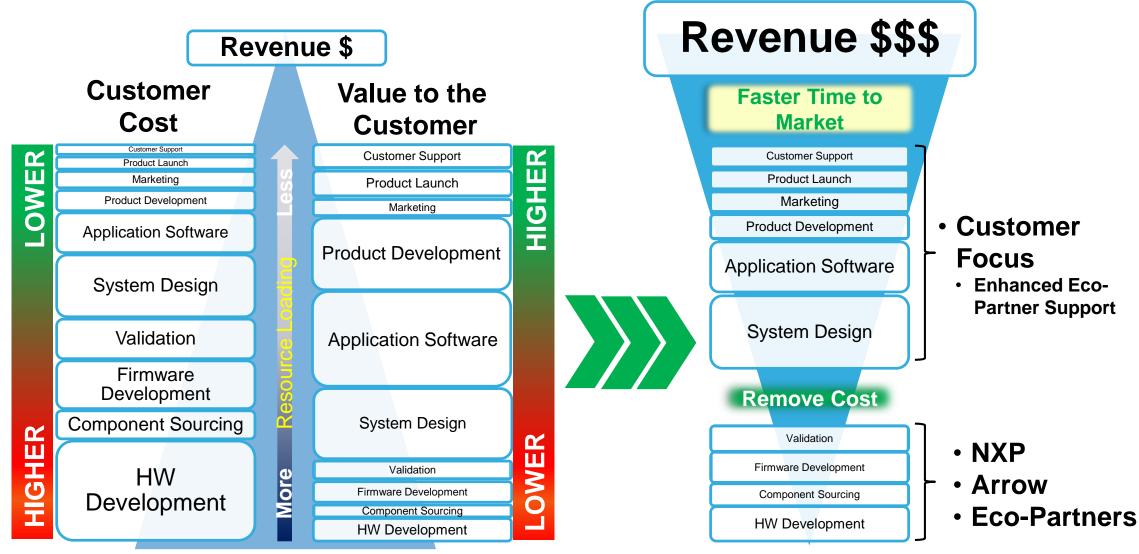
#### What emerging products need.

- More integration
- More communications
- More features
- More access
- 3 PUBLIC USE **#NXPFTF**

- More sensing
- Faster time to Market



### **Customer Value Based Costing**



NP

# INTRODUCTION TO THE SINGLE CHIP SYSTEM MODULE



### Why Choose a Single Chip System Module (SCM)?

- >50% reduction over current discrete solutions for your application board
- Reduces average development time by up to 25%
- Reduces design complexity of integrating and validating DDR memory and power management into customer design
- Eliminates extensive testing and validation for your application
- Higher level of customer enablement (hardware integration and software enablement)
- Reduces our customer's supply chain complexity
- Provide customizable option for unique customer solutions



6 PUBLIC USE **#NXPFTF** 

# PRODUCTION LAUNCHED: SCM-I.MX 6DUAL / 6 QUAD

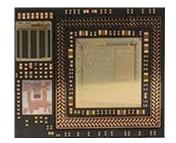


### The World's Smallest Single Chip System





#### SCM-i.MX 6D / Q Smaller than a 2-cent Euro or U.S. Dime

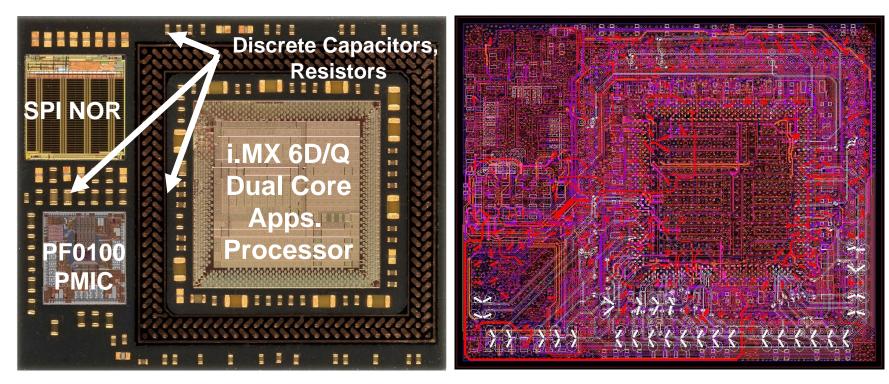




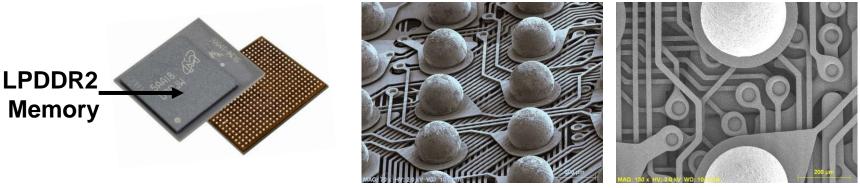
### **Production Launched February 2016**



### Family 1 SCM-i.MX 6D/6Q



- 14mm x 17mm x 1.7mm
- i.MX6Dual or i.MX6Quad
- PF0100 PMIC
- 16MB SPI NOR
- Enabled for 1GB or 2GB LPDDR2
- 109 discrete components
- 500 BGA balls P0.65mm



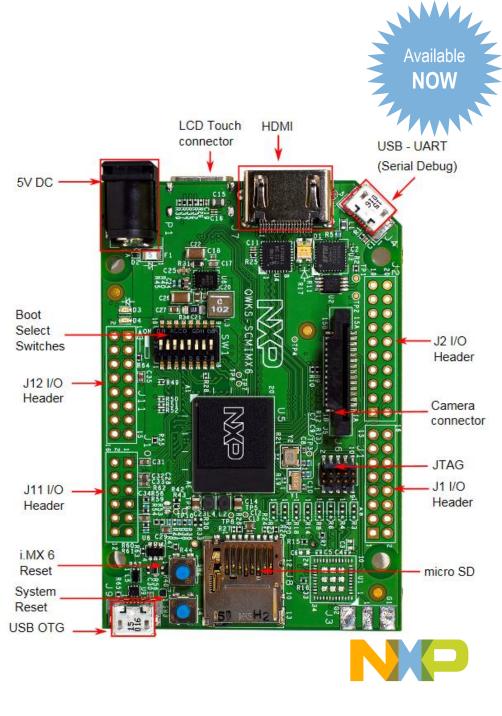


### SCM-i.MX 6Dual/6Quad Collateral

Orderable part #'s in place (NXP p/n, Arrow p/n)

				<u>.</u>			
Assembly Part Number	SCM Revision	SCM Family	DRAM	DRAM Part Number 📿	Qualification Tier		
MSCMMX6DZDK08AB	Rev1.0	SCM-i.MX6D	-	-	Commercial		
MSCMMX6QZDK08AB	Rev1.0	SCM-i.MX6Q	-	-	Commercial		
MSCMMX6DZDK08AB1G0A	Rev1.0	SCM-i.MX6D	1 GB LPDDR2	MT42L128M64D2LL-25AT:A	Commercial		
MSCMMX6DZDK08AB2G0A	Rev1.0	SCM-i.MX6D	2 GB LPDDR2	MT42L256M64D4LM-18 WT:A	Commercial		
MSCMMX6QZDK08AB1G0A	Rev1.0	SCM-i.MX6Q	1 GB LPDDR2	MT42L128M64D2LL-25AT:A	Commercial		
MSCMMX6QZDK08AB2G0A	Rev1.0	SCM-i.MX6Q	2 GB LPDDR2	MT42L256M64D4LM-18 WT:A	Commercial		

- Development boards in place along with support HW (LVDS display, MIPI camera, WLAN +BT modules, etc.
- NXP web site live (<u>www.nxp.com/scm</u>)
  - Datesheet, factsheets, users guide HW developers guide, App notes, Linux SW patch releases, etc
- Software Enablement
- Linux.
- Android (July)
- Longevity program (10yr, Feb 2026) on SCM.
- 10 PUBLIC USE **#NXPFTF**



### **Derivative Products For Family 1**

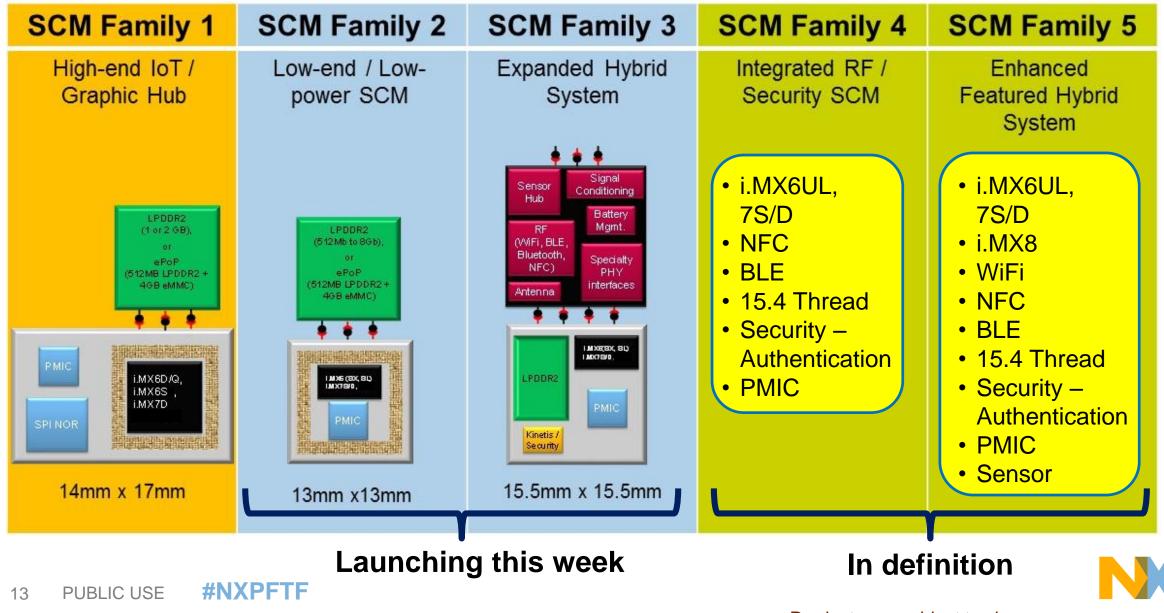
SCM	SCM Family SCM Family		Configuration	Availability		
				Beta Samples	Production	
SCM-i.MX6D (Commercial)	1		i.MX6D, PMIC, SPI-NOR, PoP LPDDR2 Memory (1 or 2 GB)		In Production	
SCM-i.MX6Q (Commercial)	1	LPDDR2 (1 or 2 GB), or ePoP (512MB LPDR2 + 4GB eWMC)	i.MX6D, PMIC, SPI-NOR, PoP LPDDR2 Memory (1 or 2 GB)		In Production	
SCM-i.MX6D ePoP (Commercial)	1	PAGE	i.MX6D, PMIC, SPI-NOR, ePoP (512MB LPDDR2 + 4GB eMMC) Memory	Available	Jun-16	
SCM-i.MX6S (Commercial)	1	SPINOR	i.MX6S*, PMIC, ePoP or LPDDR2	Jun-16	Jul-16	
SCM-i.MX6D/Q (Industrial)	1		i.MX6D/Q, PMIC, SPI-NOR, PoP LPDDR2 Memory		In Production	



# SINGLE CHIP MODULE ROADMAP



### **System Solutions Family of Products**



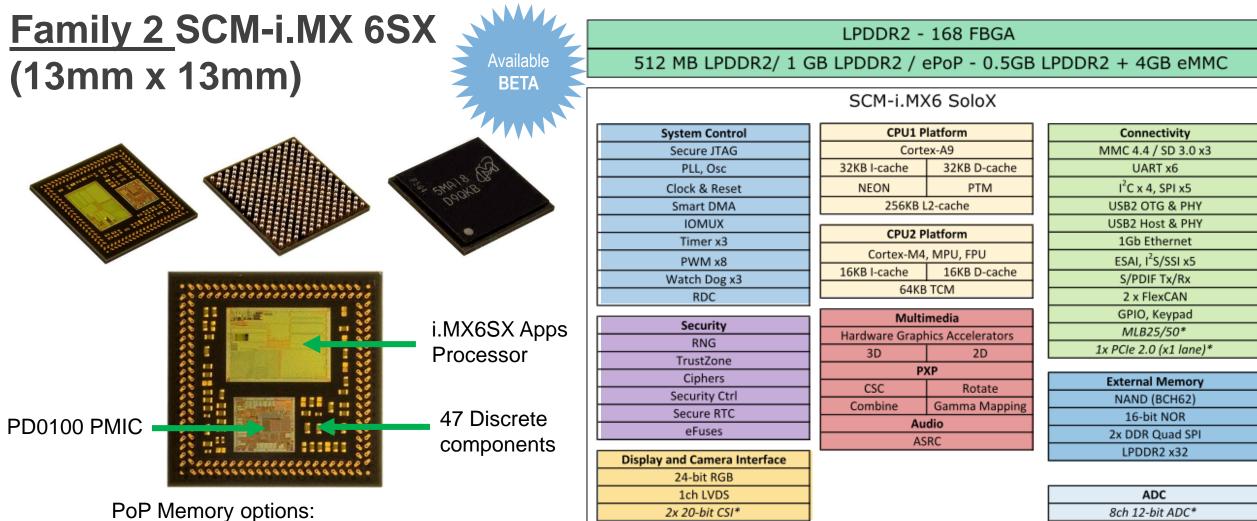
Products are subject to change

# **INTRODUCTION TO** THE TWO NEW FAMILIES IN THE SCM FAMILY



# SCM-I.MX 6SX





- 512MB, 1GB LPDDR2
- ePoP (512MB LPDDR @ + 4GB eMMC)

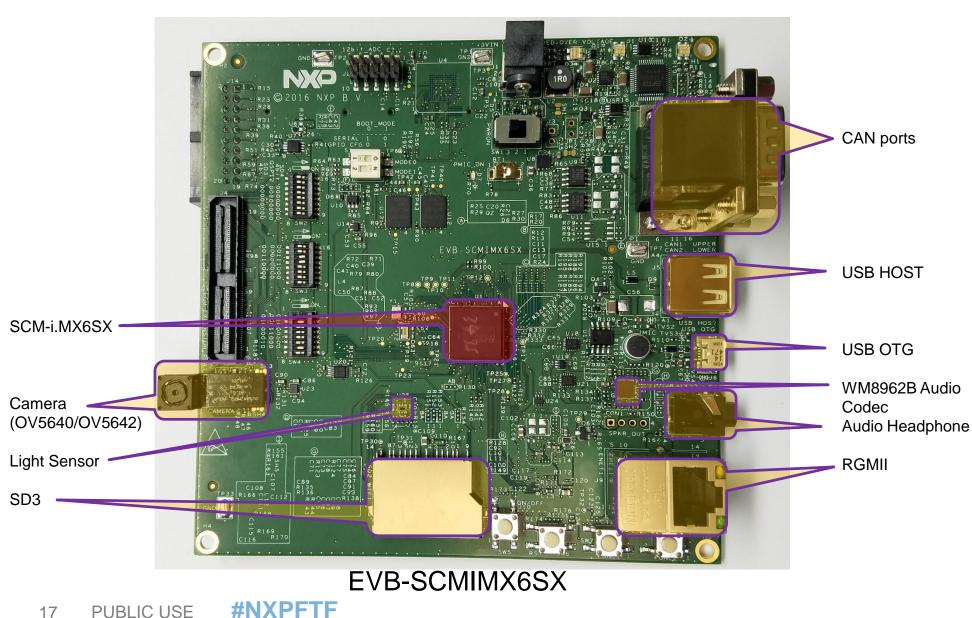
0.75mm Ball pitch (diagonal array) BSP released Enabled for Linux

Power Management - MMPF0100									
SW1AB SW1C* SW2									
SW3AB	SW4*	SWBST							
VGEN1*	VGEN2*	VGEN3							
VGEN4	VGEN5*	VGEN6							

\* These features are either unavailable or reduced in functionality on the 265BGA.



### **SCM-i.MX 6SX Evaluation Board**



#### ????

- NXP extranet site live with preliminary documentation, NDA required
  - www.nxp.com/go/scm
  - Datasheet, fact sheet, SW users guide, Linux SW patch release (beta)
  - Software Enablement
  - Linux (3.14.x kernel) beta release



# SCM-i.MX 6SX V-Link



### Motivation for Developing the SCM V-Link Hybrid Module

### What does the SCM provide

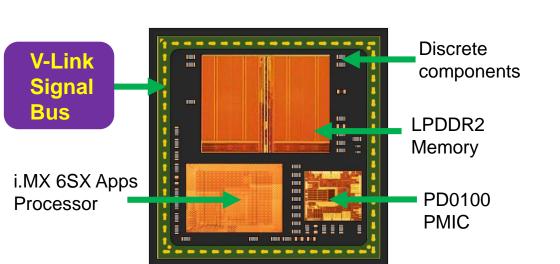
- Providing customers an integrated Application processor + PMIC + Memory
   Address design and signal integrity challenges
- Smaller form factor with high level of functionality

### What would customers also like to have

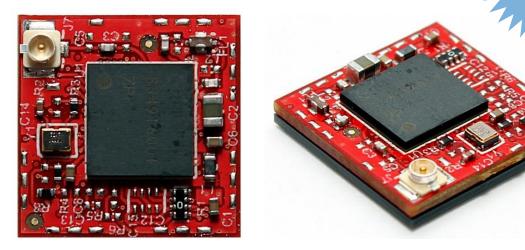
- Provide flexibility in adding their own features and functionality
   Adding RF (Wi-Fi, BLE, NFC, etc), Sensors, Audio Codex, PHY interfaces, etc.
- Ability to use contract manufactures for their own 'Top Board'
   PCB or substrates with off the shelf surface mount components



### Family 3 SCM-i.MX 6SX V-Link (15.5mm x 15.5mm)



NXP Base SCM



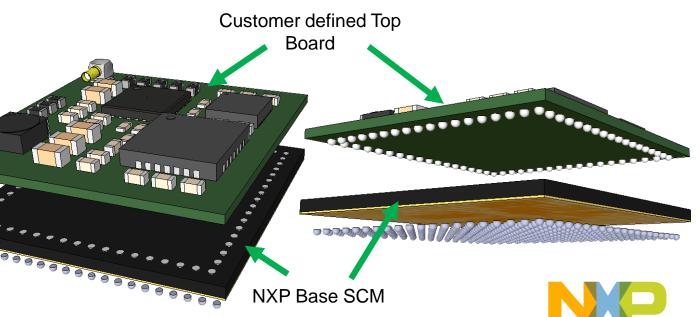
Available ALPHA

Custom Top Board (PCB or Substrate Based):

• RF, Sensors, Battery mgmt., PHY interface, Audio Codex, etc

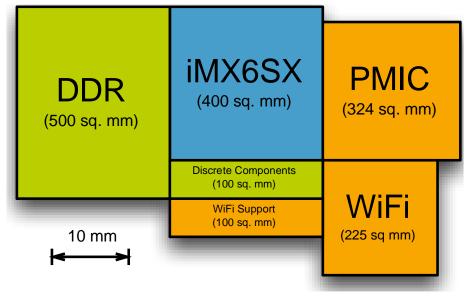
0.75mm Ball pitch

BSP released Enabled for Linux

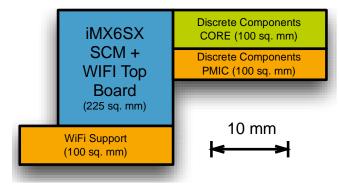


### Change in i.MX6 Design Topology

Traditional layout using discrete IC and components on a PCB board



## Equivalent PCB Board area utilizing NXP SCM with the V-Link Top Board



- 67.9% reduction is board area by utilizing the NXP Base SCM (i.MX6SX + PMIC + Memory + Discretes)
- 69.2% reduction in board area by utilizing the SCM Top Board for the WiFi + BT + Discrete module)



21



### SCM-i.MX 6SX V-Link BGA Interface

The SCMIMX6SX V-LINK modules supports the i.MX 6SX, PF0100, and LPDDR2 device interfaces

Summary of features

#### I.MX 6SX

- All user IO interfaces except the following
   ADC2, RGMII2, VADC
- All PoP signals connected to the BGA for user selection

#### **PF0100**

- All power interfaces, 6 switchers, 6 LDOs
- Switchers scaled to meet system requirements

#### 512MB LPDDR2

- Fully embedded support
- Only 1.2 V power connection required on the PCB. (PMIC interface)

#### **POP Interface**

- Two user defined power domains
- Ten Pass Thru signals for user defined IO interfaces. These pins connect from PoP to BGA
- 22 PUBLIC USE **#NXPFTF**



### SCM-i.MX6SX V-Link Bus Signaling

- V\_LINK Bus is a custom PoP interface with i.MX6 IOs and system power
- V-LINK was designed to directly support RF (Wi-Fi, BLE, NFC, 15.4, etc) Sensors and other common peripherals
- V-LINK additional supports user defined bus signals to generate a robust customizable bus
- i.MX6 Interfaces supported:
  - SDIO 4-bit
    SPI
  - > UART > I2C
  - > SSI > CAN
- PMIC powers
- Two User Defined Power Supply Rails
- 10 User Defined Pass Thru Signals (BGA to PoP)

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
A	GND	KEY_ROW2	KEY_COL2	POP_PASS_ THRU1	GND	POP_PASS_ THRU2	POP_PASS_ THRU3	POP_PASS_ THRU4	GND	POP_PASS_ THRUS	POP_PASS_ THRU6	POP_PASS_ THRU7	POP_PASS_ THRU8	GND	POP_PASS_ THRU9	POP_PASS_ THRU10	POP_PASS_ THRU11	GND
в	KEY_ROW3																	SD2_DAT1
с	KEY_COL3																	SD2_DAT0
D	KEY_ROW4																	SD2_CLK
E	GND																	GND
F	KEY_COL4																	SD2_CMD
G	GPI01_11																	SD2_DAT3
н	SYS_POR_B																	SD2_DAT2
J	GND								Version 2	2								GND
к	SYS_VGEN4_1V8																	NVCC_SD2
L	VGEN3																	GPI01_00
м	POP_PWR2																	GPI01_01
N	POP_PWR2																	NAND_DATA04
Р	POP_PWR1																	NAND_DATA05
R	POP_PWR1																	NAND_DATA06
т	VGENZ																	NAND_DATA07
U	VGEN1							V1 to V2 change	V1 to V2 change		V1 to V2 change	V1 to V2 change	V1 to V2 change					NAND_ALE
v	GND	GND	GND	GND	POP_SPARE1	USB_H_DATA	USB_H_STROBE	NVCC_KEY	NAND_CE1_B	GND	NAND_RE_B	NAND_CE0_B	NAND_WE_B	GND	NAND_CLE	NAND_WP_B	NAND_READY_B	GND



23 PUBLIC USE **#NXPFTF** 

### **SCM Development Support**

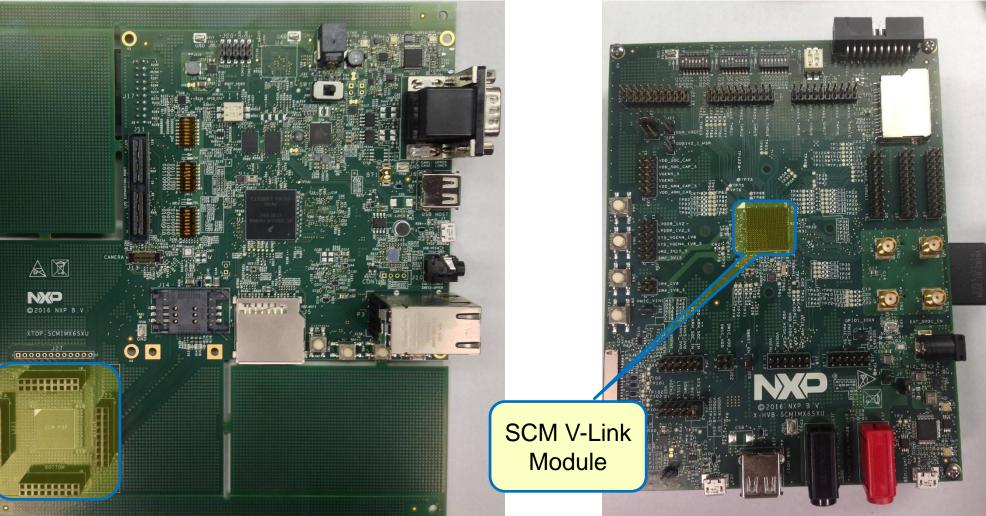
- Alpha samples available
- ECO-Partner support in place
- Development boards available

Customer Top

**Board Slot** 

#### **Top Board SW Developer**







24 PUBLIC USE **#NXPFTF** 

# PARTNER DEMOS

## **UTILIZING SCM-I.MX 6SX V-LINK**



# **BOUNDARY DEVICES**



### **Boundary Devices Introduction**

Bd Boundary Devices

- Headquarters: Chandler, Arizona USA
- Founded in 2003 (Privately Held)
- Our Business: NXP i.MX Family
- Multiple Single Board Computers and System on Modules (SOM) based on the i.MX family of processors
- Full Software Support package including Yocto, Ubuntu, Android 5.0, Buildroot, WinCE 7, and QNX Operating Systems
- NXP Proven Partner



Nitrogen6X\_SOM



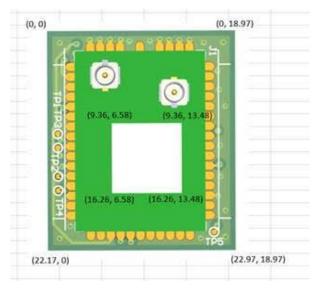
SABRE Lite BD-SL-i.MX6



### SCM Carrier Board + V-Link Top Board

- Adding WiFi+BT to SCM can be done in 2 ways: via Carrier board or Top board
- Carrier board requires horizontal space which many applications do not have.
- Space savings of 280 mm sq
- V-Link Top Board from Boundary Devices QCA9377 802.11ac + BT4.1 module. Pre-certified and ready for production. Mounts on top of SCM which is ideal for space constrained applications. 22mm x 19mm board dimensions
- Available Linux/Android Drivers for easy WiFi+BT software integration for kernel 3.14.28 and above
- On 5GHz network utilizing SDIO 3.0, WiFi throughput is 90Mb/s









# Boundary Devices SCM Demo Application Bd Boundary Devices



- V-Link Top board is ideal for handheld/space-constrained applications allowing customers to integrate vertically
- Boundary Devices demo is a handheld, battery powered wireless streaming application. The demo consists of NXP SoloX SCM + BD V-Link Top board with 802.11ac module + BD Carrier board with 5MP MIPI Camera and Battery.
- The demo application wirelessly streams data from the 5MP camera on the handheld device to a desktop board which shows the stream on a 7" display
- There is a point-to-point link from the handheld device to the desktop device
- Visit demo at the NXP booth in the Technology lab





## PHALAX ULTRA-COMPACT BORDER ROUTER



### Sub-GHz Wireless Mesh Networks using 6SX V-Link

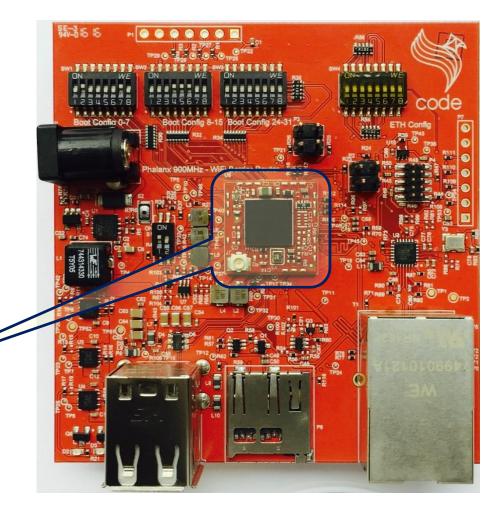
### Ultra Compact Sub-GHz to WiFi Border Router solution

### -Applications:

- Home Automation
- Wireless Sensor Nodes
- Smart Lighting
- Smart City
- Smart Meters
- Smart Parking
- IoT



SCM-i.MX 6SX V-Link w/ Top Board





### **Phalanx Ultra-Compact Border Router**

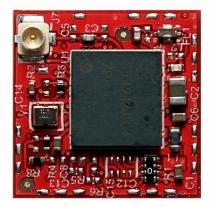
### Top Board

- -2.4 GHz & 5 GHz WiFi/BT 4.0 + EDR
- -802.11 a/b/g/n/ac
- Up to 390 Mbps
- -U.FL standard antenna connector
- Broadcom BCM4339 Chipset
- iMX 6SX V-Link Top Board form factor
- –15.5 x 15.5 mm



### Phalanx Border Router

- Optimized mesh network for sensing and control applications
- Highly scalable, minimizing deployment costs
- -900 MHz Wireless
- A new, clever routing algorithm which reduces routing overhead.
- -Fully IPv6





### **Design Process**

### Conceptualization

 The iMX 6SX V-Link is one of the most capable yet compact application processor platforms. We envisioned using this platform to open a wide range of IoT possibilities.

### Design

- iMX 6SX V-Link, presents the right choice of buses and IOMUX options which made the design straightforward. Our schematic and PCB capture time was less than 2 weeks of effort.
- V-Link technology allowed us to route all the needed connections easily and within electrical specs.



### **Design Process**

### **Prototyping and Testing**

- Top Board PCB is highly flexible, it was a pleasant surprise to find that all our components fitted nicely in the design.
- Testing was quite easy with all the software provided by NXP.

### **Design Cycle time**

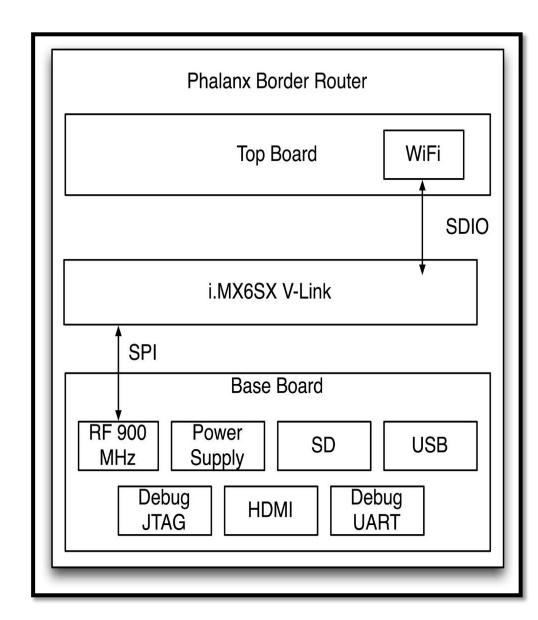
- In just 2 months the whole solution was up and running, including software porting, PCB layout, manufacturing and assembly.
- The exceptional level of integration provided by this new NXP platform enabled us to add extra features to the design such as last generation 802.11 ac WiFi a conventional approach would have taken us around 4 to 6 months.
- Thus, we have reduced time to market by up to 4 months.



### Summary

### **Benefits**

- -Ultra compact, ready to deploy IoT Top Board solution
- -High level of hardware and software integration enables customers with a powerful solution and a very short time to market
- Phalanx software provides powerful low latency IoT IPv6 mesh technology
- Visit demo at the NXP booth in the Technology lab





# FIRSTVIEW

## MEDICAL WEARABLE GATEWAY



### **FirstView Consultants Introduction**

- NXP i.MX Family Experts
- Dozens of i.MX designs for clients including the FirstView i.MX6 SOM and Carrier Board
- Provide turn key solutions for hardware, software and manufacturing
- Software solution on Linux, Android, iOS and WinCE
- NXP, Arrow and Future Partner
- Based right here in Austin, Texas
- Founded 2010









### V-Link SCM enabling a Wearable Medical Monitoring Device.



## Limitations of Monitoring devices available today

- Not convenient to wear for continuous monitoring
- Not directly connected to cloud to provide life saving alerts
- Require user to connect wires





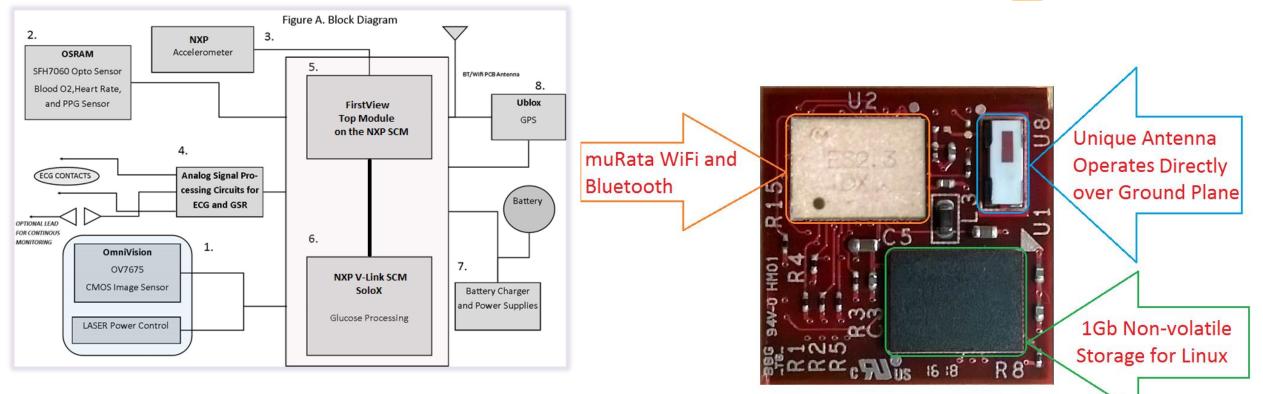
## GPS enabled medical monitor for detecting and transmitting via integrated Wi-Fi and Bluetooth

- Pulse Oximeter Blood oxygen
- Galvanic Skin Response (GSR) Stress levels
- Accelerometer Fall detection
- Skin and ambient temperature
- Photoplethysmogram (PPG) Heart rate and blood pressure
- Electrocardiogram (ECG)- Heart rate, heart duress
- Continuous Glucose Monitor- Blood sugar monitor



### Wearable Top Module and SCM Block Diagram





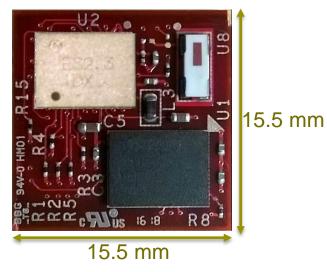
High Level Block Diagram on the Wearable Design

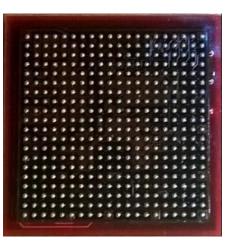
FirstView Top Module mounted on to the NXP V-Link SCM



### **Benefits of V-link SCM and FirstView Top Module**

- The SCM-i.MX 6SX V-Link has enabled FirstView to develop this product
  - The risk of DDR SDRAM integrity was completely removed as it is part of the SCM
  - The SCM has the High Speed RAM and Power Management Integrated which otherwise takes 2 months to design
  - Ultra-compact 15.5mm x 15.5mm
  - Existing reliable BSP with drivers available with V-Link SCM
- Summary the benefits of the wearable application
  - Cloud-Connected ECG
  - Battery Operated
  - IoT Medical ECG Alert
  - Life Saving Monitoring
  - Linux Based Platform Providing Extensibility
- Visit demo at the NXP booth in the Technology lab
  - 40 PUBLIC USE **#NXPFTF**







# SUMMARY



### Summary

- SCM products are designed to enable the <u>smallest form factor</u>, <u>feature enabled</u> and <u>highly integrated</u> solution to help significantly *reduce the customers complexity and time to market*
- NXP is launching multiple families of SCM Modules to meet different markets and customer needs
- Alpha, Beta and Production parts and development boards are <u>available now</u>.
   Contact
  - Amanda McGregor: Product Marketing and Application Support
    - Tel: 512-895-8501
    - <u>Amanda.mcgregor@nxp.com</u>



### SCM Demo's and Contact Info.

- SCM Demo's in the Tech. Lab
  - SCM-i.MX6D/Q with ePoP (LPDDR2+eMMC)
  - SCM-i.MX6SX
  - SCM-i.MX6SX V-Link Boundry Devices
  - SCM-i.MX6SX V-Link Code
  - SCM-i.MX6SX V-Link Firstview
  - SCM-i.MX6Dual / 6Quad integrated with NFC

#### Contact Info

- Navjot Chhabra: Product and Business Development
  - Tel: 512-895-6470
  - <u>Navjot.chhabra@nxp.com</u>
- Amanda McGregor: Product Marketing and Application Support
  - Tel: 512-895-8501
  - <u>Amanda.mcgregor@nxp.com</u>
- http://www.nxp.com/products/single-chip-modules

Micron Technology Booth Arrow & NXP Booth NXP Booth NXP Booth NXP Booth NXP Booth \*\* Win a Quickstart Board \*\*









### SECURE CONNECTIONS FOR A SMARTER WORLD

#### ATTRIBUTION STATEMENT

NXP, the NXP logo, NXP SECURE CONNECTIONS FOR A SMARTER WORLD, CoolFlux, EMBRACE, GREENCHIP, HITAG, I2C BUS, ICODE, JCOP, LIFE VIBES, MIFARE, MIFARE, MIFARE Classic, MIFARE DESFire, MIFARE Plus, MIFARE FleX, MANTIS, MIFARE ULTRALIGHT, MIFARE4MOBILE, MIGLO, NTAG, ROADLINK, SMARTLX, SMARTMX, STARPLUG, TOPFET, TrenchMOS, UCODE, Freescale, the Freescale logo, AltiVec, C 5, CodeTEST, CodeWarrior, ColdFire, ColdFire+, C Ware, the Energy Efficient Solutions logo, Kinetis, Layerscape, MagniV, mobileGT, PEG, PowerQUICC, Processor Expert, QorIQ, QorIQ Qonverge, Ready Play, SafeAssure, the SafeAssure logo, StarCore, Symphony, VortiQa, Vybrid, Airfast, BeeKit, BeeStack, CoreNet, Flexis, MXC, Platform in a Package, QUICC Engine, SMARTMOS, Tower, TurboLink, and UMEMS are trademarks of NXP B.V. All other product or service names are the property of their respective owners. ARM, AMBA, ARM Powered, Artisan, Cortex, Jazelle, Keil, SecurCore, Thumb, TrustZone, and µVision are registered trademarks of ARM Limited (or its subsidiaries) in the EU and/or elsewhere. ARM7, ARM9, ARM11, big.LITTLE, CoreLink, CoreSight, DesignStart, Mali, mbed, NEON, POP, Sensinode, Socrates, ULINK and Versatile are trademarks of ARM Limited (or its subsidiaries) in the EU and/or elsewhere. All rights reserved. Oracle and Java are registered trademarks of Oracle and/or its affiliates. The Power Architecture and Power.org word marks and the Power and Power.org logos and related marks are trademarks and service marks licensed by Power.org. © 2015–2016 NXP B.V.

NXP Semiconductors is licensed by EPIC Technologies Inc. to make and sell packages that include Epic's "Chips First" technology and related patents.

